

Application Data Sheet

Application Information

Application Type::	Regular
Subject Matter::	Utility
Suggested Classification::	
Suggested Group Art Unit::	
CD-ROM or CD-R?::	None
Number of CD disks::	
Number of Copies of CDs::	
Sequence Submission?::	None
Computer Readable Form (CRF)::	No
Number of copies of CRF::	0
Title::	SEMICONDUCTOR PACKAGE, AND PRODUCTION PROCESS FOR MANUFACTURING SUCH SEMICONDUCTOR PACKAGE
Attorney Docket Number::	8053-1015
Request for Early Publication?::	No
Request for Non-Publication?::	No
Suggested Drawing Figure::	
Total Drawing Sheets::	18
Small Entity?::	No
Latin Name::	
Variety Denomination Name::	
Petition Included?::	No
Petition Type::	
Licensed US Gov't Agency::	
Contract or Grant Numbers::	
Secrecy Order in Parent Appl.?::	No

Applicant Information

Applicant Authority Type:: Inventor
Primary Citizenship Country:: JAPAN
Status:: Full Capacity
Given Name:: TAKEKAZU
Middle Name::
Family Name:: TANAKA
City of Residence:: KAWASAKI-SHI, KANAGAWA
State or Province of
Residence::
Country of Residence:: JAPAN
Street of Mailing 1753 SHIMONUMABE, NAKAHARA-KU
Address::
City of Mailing Address:: KAWASAKI-SHI, KANAGAWA
State or Province of Mailing Address::
Country of Mailing Address:: JAPAN
Postal or Zip Code of Mailing Address::

Correspondence Information

Correspondence Customer 000466
Number::

Representative Information

Representative Customer	000466
Number::	

Domestic Priority Information

Application::	Continuity Type::	Parent Application::	Parent Filing Date::

Foreign Priority Information

Country::	Application Number::	Filing Date::	Priority Claimed::
JAPAN	2002-237731	8/19/02	Yes

Assignment Information

Assignee Name:: NEC ELECTRONICS CORPORATION

Street of Mailing 1753 Shimonumabe, Nakahara-ku

Address::

City of Mailing Address:: KAWASAKI-SHI, KANAGAWA

State or Province of Mailing Address::

Country of Mailing Address:: JAPAN

Postal or Zip Code of Mailing Address::